

## **REMARKS**

In view of the above amendments and following remarks, reconsideration and further examination are requested.

Initially, the Examiner's attention is respectfully directed to the Information Disclosure Statement filed July 21, 2004.

The Examiner has objected to the Amendment filed January 15, 2004, for introducing new matter into the disclosure. The Examiner has rejected claims 94-124 under 35 U.S.C. § 112, first paragraph, for containing new matter. And, the Examiner has rejected claims 39-54, 56, 57, 77-79, 83-86, 88, 90-92 and 94-124 over a combination of a plurality of references for a variety of reasons. These rejections are respectfully traversed for the following reasons.

The prior art rejections are believed to be improper for the same reasons as presented in the Response filed January 15, 2004. Accordingly, the traversal of the 35 U.S.C. § 103(a) rejection as set forth in the January 15 Response is hereby repeated.

In response to the new matter rejection of claims 115 and 122, these claims have been amended to delete therefrom the limitation that the circuit board is softened.

The new matter rejection of claim 94, and objection to the Amendment filed January 15, 2004, for introducing new matter into the disclosure, are respectfully traversed for the following reasons.

The objection to the January 15 Amendment and the 35 U.S.C. § 112, first paragraph, rejection of claim 94, are both based on the Examiner's conclusion that the original specification provides no support for application of heat to the circuit board substantially simultaneously with commencement of application of pressure to the circuit board. While it is not disputed that the original specification does not literally recite that commencement of application of heat to the circuit board occurs substantially simultaneously with commencement of application of pressure to the circuit board, it is respectfully submitted that the recitation of this feature does not constitute new matter. Specifically, from a fair consideration of Figure 5E and its description, it is respectfully submitted that support exists for commencement of application of heat to the circuit board occurring substantially simultaneously with commencement of application of pressure to the circuit board.

In this regard, the sentence bridging pages 32 and 33 of the original specification states

Next, as shown in Fig. 5E, the IC chip 1 on which the

bumps 3 have been formed through the aforementioned processes are aligned in position with the electrodes 5 that belong to the board 4 prepared through the aforementioned processes and correspond to the IC chip 1, and are **pressed** via the anisotropic conductive film sheet 10, **by the heated bonding tool 8**. (emphasis added)

As shown in Figure 5E, the circuit board 4 is in a state in which no pressing of the circuit board 4 is being performed. The pressing does not occur until the bonding tool 8 forces the bumps 3 on IC chip 1 against conductive film sheet 10 located on circuit board 4, and at some time prior to this pressing being performed, as is evident from a clear reading of the above-quoted sentence, the bonding tool 8 is in a heated state. Accordingly, upon commencement of forcing of the IC chip 1 against the conductive film sheet 10 via the heated bonding tool 8, heat and pressure will be transferred to the circuit board 4 substantially simultaneously. That is, because heat is not transferred to the circuit board 4 until the conductive film sheet 10 is contacted by IC chip 1, and because mutual pressing between the IC chip 1 and the circuit board 4 also does not occur until the IC chip 1 is pressed against the conductive film sheet 10, heat is applied to the conductive film sheet 10 substantially simultaneously with the mutual pressing between the IC chip 1 and the circuit board 4.

In view of the above, it is respectfully submitted that the language objected to by the Examiner for introducing new matter into the disclosure basically corresponds to a re-phrasing of the description of what is shown and described with reference to Figure 5E, and as expressed in MPEP 2163.07, re-phrasing of a passage does not constitute new matter. Accordingly, in view of the above, it is respectfully submitted that the objection to the Amendment of January 15, 2004 for adding new matter to the specification should be withdrawn, along with the 35 U.S.C. § 112, first paragraph, rejection of claims 94-124 as introducing new matter.

If the Examiner continues to reject claim 94 as introducing new matter, then the Examiner is respected to specifically explain how Figure 5E and its description does not provide support for commencement of mutual pressing and commencement of application of heat occurring substantially simultaneously.

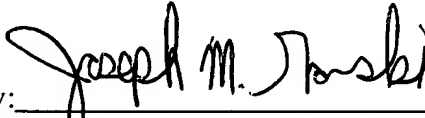
Also, because claim 55 was not addressed in the body of the rejection on pages 2-10 of the Office Action, this claim is presumed to constitute allowable subject matter and thus has been rewritten in independent form.

In view of the above amendments and remarks, it is respectfully submitted that the present application is in condition for allowance and an early Notice of Allowance is earnestly solicited.

If after reviewing this Amendment, the Examiner believes that any issues remain which must be resolved before the application can be passed to issue, the Examiner is invited to contact the Applicant's undersigned representative by telephone to resolve such issues.

Respectfully submitted,

Kazuto NISHIDA

By: 

Joseph M. Gorski  
Registration No. 46,500  
Attorney for Applicant

JMG/edg  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
October 6, 2004